

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1. (currently amended): A method of forming a composite insulating layer, comprising:

a step of forming an adhesive layer containing a partially imidated polyamic acid on a metallic foil;

a step of applying a solution containing a polyamic acid to the surface of the adhesive layer;

a step of subjecting the coated solution to phase separation to form a porous layer; and

a step of subjecting the adhesive layer and the porous layer to imide conversion,

wherein the partially imidated polyamic acid has a ratio  $RA (= A1/A2)$  of an absorbance  $A1$  derived from a C=O bond of an imido ring to an absorbance  $A2$  derived from a C=O bond of an amide acid in the infrared absorption spectrum of 0.1-5.0.

2. (canceled).

3. (original): The method as claimed in claim 1, wherein the step of forming an adhesive layer comprises applying a solution containing a polyamic acid to the surface of the

metallic foil, and then conducting drying of a solvent contained therein and partial imidation of the polyamic acid, by heating.

4. (withdrawn): A composite insulating layer formed by the method as claimed in claim 1.

5. (currently amended): A process of producing a wiring board, comprising a step of forming ~~a~~an insulating layer and a step of forming a wiring layer, wherein the step of forming ~~a~~an insulating layer is carried out to form the insulating layer by the method as claimed in claim 1.